

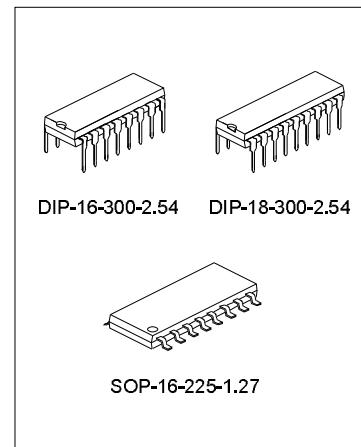
T/P SWITCHABLE DIALER WITH REDIAL HANDFREE FUNCTION

DESCRIPTION

The SC91710A/B are Tone/Pulse switchable dialer which are fabricated in COMS technology with wide operating voltage for both tone and pulse mode, and consumes very low memory retention current in ON-HOOK state.

FEATURES

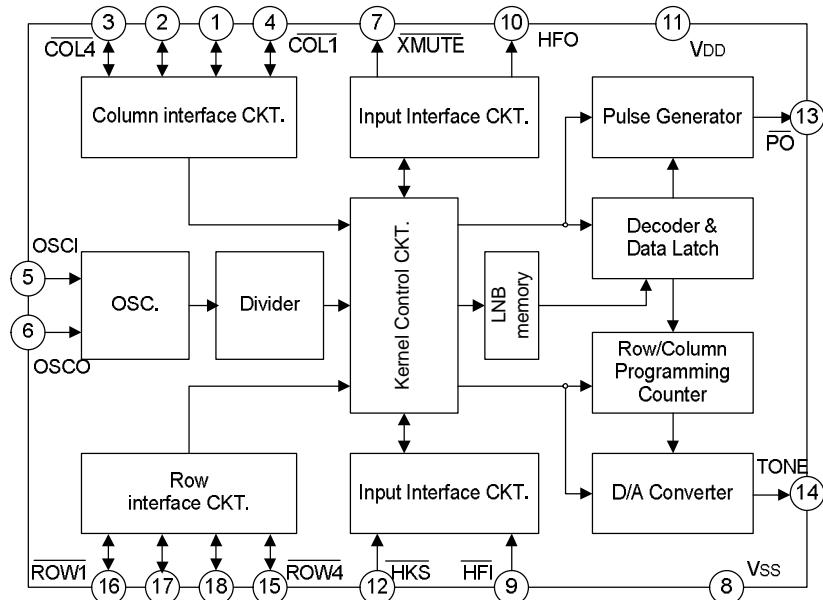
- * Tone/Pulse switchable dialer
- * One 32-digit last number redial memory
- * Pulse-to-tone (P→T) is provided for PBX operation
- * Flash key is available
- * Minimum tone duration is 98ms or 83ms
- * Minimum intertone pause is 98ms or 83ms
- * Redial Pause time (0ms)
- * Uses 3.579549MHz crystal or ceramic resonator
- * Many options can be selected
 - Mode (10PPS; 20PPS; Tone)
 - M/B ratio (40:60;33:66)
 - Pause time (3.6s)
- * Flash function (RESET)
 - (P→T) pause time (3.6s)
 - Flash time (600ms; 300ms; 100ms; or 80ms)
- * Power on reset circuit is provided
- * Handfree function is provided for speaker phone application
- * Packaged in 16-DIP or 18-DIP



ORDERING INFORMATION

Device	Package
SC91710A	DIP-16-300-2.54
SC91710AS	SOP-16-225-1.27
SC91710B	DIP-18-300-2.54

BLOCK DIAGRAM



KEYBOARD ASSIGNMENT

	C1	C2	C3	C4
R1	1	2	3	P→T
R2	4	5	6	F
R3	7	8	9	P
R4	*	0	#	RD

- 1) P→T: In pulse mode, execute P→T function.
- 2) P: Pause key.
- 3) F: Flash key
- 4) RD: Redial key

DIALING SIGNAL OPTION

A: Flash time

Row3	Row4	Flash time(ms)
NR	NR	600
NR	R	300
R	NR	100
R	R	80

B:

Row1	Row2	MODE	PULSE RATE	M/B
R	NR	TONE	--	--
R	R	TONE	--	--
NR	NR	PULSE	20PPS	40:60
NR	R	PULSE	20PPS	33:66
UR	NR	PULSE	10PPS	40:60
UR	R	PULSE	10PPS	33:66

C: Tone function

Col1	Tone Duration	Inter-Tone Pause
NR	98ms	98ms
R	83ms	83ms

Note: NR: no resistance

R: A resistance connect to Vss (820kΩ typically)

UR: A resistance connect to VDD

ABSOLUTE MAXIMUM RATING($T_{amb}=25^{\circ}C$, All voltage referenced to Vss, unless otherwise specified)

Characteristics	Symbol	Ratings			Unit
Power Supply Voltage	VDD	6.0			V
Input Voltage	VIN	-0.3~VDD+0.3			V
Power Dissipation	PD	500			mW
Operating Temperature	Topr	-25~+70			°C
Storage Temperature	Tstg	-55~+150			°C

ELECTRICAL CHARACTERISTICS($T_{amb}=25^{\circ}C$, $VDD=2.5V$, $fosc=3.579545MHz$, unless otherwise specified)

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit
DC Characteristics						
Operating Voltage	VDD	Tone	2.5	--	5.5	V
		Pulse	2.0	--	5.5	
		Memory retention	1.0		5.5	
Operating Current	IOP	Tone	OFF-HOOK,	0.6	2	mA
		Pulse	Keypad entry	--	0.2	
Standby Current	Is	ON-HOOK, No keypad entry	--	0.1	1	μA
Memory Retention Current	Imr	ON-HOOK, $VDD=1.0V$	--	0.1	0.2	μA
Control Pin Input Low Voltage	Vil	--	Vss		0.3VDD	V
Control Pin Input High Voltage	Vih	--	0.7VDD		VDD	
XMUTE Pin Leakage Current	Imth	$V_{XMUTE}=6.0V$	--	--	1	μA
XMUTE Pin Sink Current	Imtl	$V_{XMUTE}=0.5V$	0.2	0.5	--	mA
HKS Pin Input Current	Ihks	$V_{HKS}=2.5V$	--	--	0.1	μA
Keyboard Drive Current	Ikbd	$V_n=0V$ (note1)	4	10	30	μA
Scanning Pin Sink Current	Ikbs	$V_n=2.5$ (note1)	200	400	800	
Key-in Debounce Time	tDB	--	--	20	--	ms
HFI pin input resistor	Rhfi	$VDD=2.5$	--	200	--	kΩ
HFO pin drive current	Ihdoh	$V_{HFO}=2.0V$	0.5	--	--	mA
HFO pin sink current	Ihdol	$V_{HFO}=2.5V$	0.5	--	--	mA
Pulse Mode						
Pulse Output Pin Leakage Current	Ipoh	$V_{PO}=2.5V$	0.1	--	--	μA
Pulse Output Pin Sink Current	Ipol	$V_{PO}=0.5V$	0.5	--	--	mA
Pulse Rate	fpr		--	10	--	pps
			--	20	--	
Make/Break Ratio	tM: tb		--	40:60	--	%
			--	33:66	--	
Pre-digit Pause	tPDP	M/B ratio=40:60	--	40	--	ms
		M/B ratio=33:66	--	33	--	

(To be continued)

(Continued)

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit
Inter-digit Pause	tIDP	Pulse rate=10pps	--	800	--	ms
		Pulse rate=20pps	--	500	--	
Tone Mode						
Tone Output Pin	DC Level	Vdc	VDD=2.0V~5.5V	0.5VDD	--	0.7VDD
	Sink Current	Itl	Vdtmf=0.5V	0.2	--	--
	AC level	Vdtmf	Row group, RL=10KΩ	130	155	170
	Load Resistor	Rl	Dist.≤ -23dB	10	--	--
DTMF Signal	Pre-emphasis	twist	VDD=2.0~5.5 V, Column-Row group	1	2	3
	Distortion(note 2)	Dist.	RL=10KΩ	--	-30	-23
Minimum tone duration Time		tTD	Auto redial	--	98/83	--
Minimum Intertone Pause Time		tITP	Auto redial	--	98/83	--
ms						

Note: 1. Vn: Input voltage of any keyboard scanning pin (Row group, Column group)

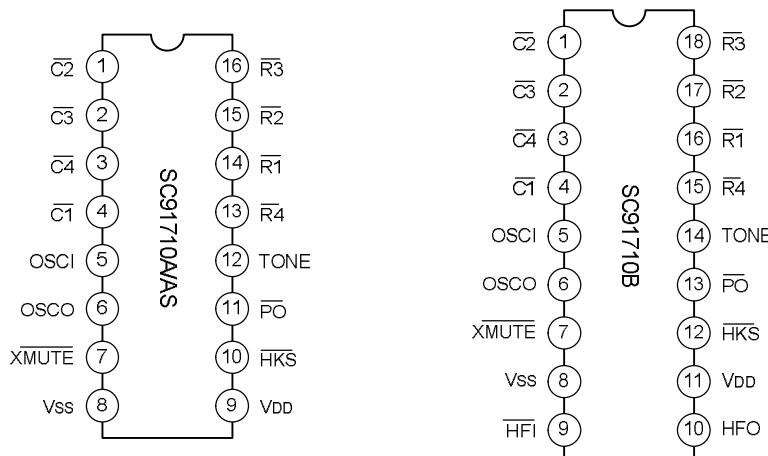
2. Distortion (dB) = $20\log\{[V_1^2 + V_2^2 + V_3^2 + \dots + V_n^2]^{1/2}\}/[(V_L^2 + V_H^2)^{1/2}]\}$

VL,VH: Row group and Column group signal , V1, V2..., Vn: Harmonic signal (BW = 300Hz~3500Hz)

ACTUAL FREQUENCY OUTPUT (fosc=3.579545MHz)

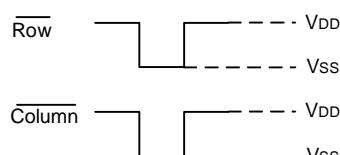
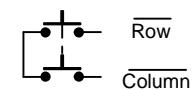
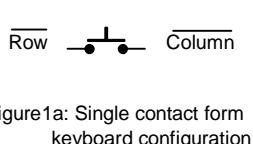
Keyboard Scanning Pin	Standard(Hz)	Output	Deviation(%)
R1	f1	697	+0.28
R2	f2	770	-0.52
R3	f3	852	-0.47
R4	f4	941	+0.74
C1	f5	1209	+0.57
C2	f6	1336	-0.30
C3	f7	1477	-0.34

PIN CONFIGURATION



PIN DESCRIPTION

Pin No.		Pin Name	Description
SC91710A/AS	SC91710B		
4	4	$\overline{C1}$	<ul style="list-style-type: none"> * Provides keyboard scanning. * \overline{HKS} pin is LOW, the column group stays in "HIGH" state and row group stays in "LOW" state.
1	1	$\overline{C2}$	
2	2	$\overline{C3}$	
3	3	$\overline{C4}$	
14	16	$\overline{R1}$	
15	17	$\overline{R2}$	
16	18	$\overline{R3}$	
13	15	$\overline{R4}$	
5	5	OSCI	<ul style="list-style-type: none"> * Oscillator input & output pins. * The 3.579545MHz oscillator is formed by a built-in inverter inside of this chip and by connecting a 3.579545MHz crystal or a ceramic resonator across the OSCI and OSCO pins. (built-in feedback resistor and capacitor)
6	6	OSCO	<ul style="list-style-type: none"> * When \overline{HKS} is "LOW", a valid key-in may turn on this oscillator and generates a 3.579545 MHz clock.
7	7	XMUTE	<ul style="list-style-type: none"> * Mute output pins. * NMOS open drain output structure. * The output is in "LOW" state during dialing sequence (both Pulse and Tone mode) otherwise this pin is "high-impedance". * Long (continue) Mute.
8	8	Vss	* Negative power supply pin.
9	11	VDD	* Positive power supply pin.



(To be continued)

(Continued)

Pin No.		Pin Name	Description
SC91710A	SC91710B		
10	12	\overline{HKS}	<ul style="list-style-type: none"> * Hook switch input pin. * When the handset is in ON-HOOK state, this pin must be pulled "high" in order to disable the dialing operation and decrease the power consumption. * When in OFF-HOOK state, the \overline{HKS} pin must be pulled "low" state for all function operation.
11	13	\overline{PO}	<ul style="list-style-type: none"> * Pulse output signal pin. * NMOS open drain output structure. * The output is "LOW" during pulse dialing and Flash operation, otherwise this output is "floating".
12	14	TONE	<ul style="list-style-type: none"> * Dual Tone Multi-frequency output pin. * In TONE mode, when an entry of digit key (include *, # key), this pin will send out a corresponding DTMF signal. * The TONE pin provides minimum tone duration and minimum intertone pause time to support rapid key-in. If key-in time is less than 100ms, DTMF signal will last for 100ms; otherwise the tone duration will last as long as the key is pressed.
	9	\overline{HFI}	<ul style="list-style-type: none"> * Handfree input control pin. * Toggle input structure, falling edge trigger. * It is used to enable and disable Handfree function. * With waveshaped by a built-in Schmitt trigger, the bounce of input can be eliminated by external R, C debounce circuit. * A built-in pull down resistor is 200k typical.
	10	HFO	<ul style="list-style-type: none"> * Handfree output control pin. * Inverter output structure (normally 'low', active 'high'). * When a HFI pin is active, Handfree function will be enabled (HFO=1) or disable (HFO=0). * When the Handfree function is enable (HFO=1), after OFF-HOOK action, it can reset Handfree function and HFO pin return to 'low' state.

KEYBOARD OPERATION

Symbol definitions:

- a) \uparrow : OFF-HOOK or enable Hand Free function.
- b) \downarrow : ON-HOOK or disable Hand Free function.
- c) $\underline{\uparrow}$: Input level from low to high.
- d) $\underline{\downarrow}$: Input level from high to low.
- e) D1~Dn : Digit key; 1, 2, 3, 4, 5, 6, 7, 8, 9, 0, *, #, (C1~Cn is same as D1~Dn).
- f) Dp1~Dpn : Pulse digit; 1, 2, 3, 4, 5, 6, 7, 8, 9, 0, (Cp1~Cpn is same as Dp1~Dpn).
- g) Dt1~Dtn : Tone digit; 1, 2, 3, 4, 5, 6, 7, 8, 9, 0, *, #, (Ct1~Ctn is same as Dt1~Dtn).
- h) t_F : Flash time.
- i) t_P : Pause time.
- j) t_{PT} : Pulse to Tone wait time.
- k) t_{FP} : Pause time for flash.
- l) t_{RP} : Pause time for redial.
- m) LNB : Last number redial buffer.

A) Normal Dialing

1. Digit Dialing

- Procedure : \uparrow D1, D2..., Dn \downarrow
- Dial out : Dt1, Dt2..., Dtn (in Tone mode)
- Dial out : Dp1, Dp2..., Dpn (in Pulse mode)
- LNB : D1, D2..., Dn

2. Dialing with flash key

- Procedure : \uparrow F, D1, D2..., Dn \downarrow
- Dial out : t_F , t_{FP} , Dt1, Dt2..., Dtn (in Tone mode)
- Dial out : t_F , t_{FP} , Dp1, Dp2, ..., Dpn (in Pulse mode)
- LNB : D1, D2..., Dn

3. Dialing with P→T key

- Procedure : \uparrow D1, D2 ..., P→T , ..., Dn \downarrow
- Dial out : Dp1, Dp2, ..., t_{PT} , ..., Dpn (in Pulse mode)
- LNB : D1, D2 ..., P→T , ..., Dn

Note: If key in digit over maximum digit stored in LNB, then RD is inhibit even after on/off hook.

B) Redial

- LNB : D1, D2..., Dn
- Procedure : \uparrow RD \downarrow
- Dial out : t_{RP} , Dt1, Dt2..., Dtn (in Tone mode)
- Dial out : t_{RP} , Dp1, Dp2,..., Dpn (in Pulse mode)

Note: If key in digit over maximum digit stored in LNB, then RD is inhibit.

C) Pause Function

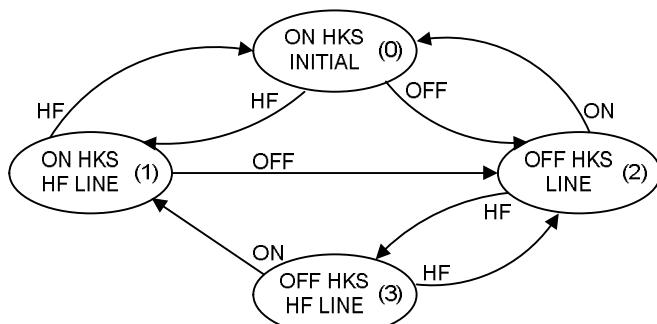
Procedure : $\uparrow D_1, D_2 \dots, D_n, P, C_1 \dots, C_n \downarrow$
 Dial out : $D_{t1}, D_{t2}, \dots, D_{tn}, t_P, C_{t1}, C_{tn}$ (in Tone mode)
 Dial out : $D_{p1}, D_{p2}, \dots, D_{pn}, t_P, C_{p1}, \dots, C_{pn}$ (in Pulse mode)
 LNB : $D_1, D_2 \dots, D_n, P, C_1, C_2 \dots, C_n$

D) Flash Function
1. Reset

Procedure : $\uparrow D_1, D_2 \dots, D_n, F, C_1 \dots, C_n \downarrow$
 Dial out : $D_{t1}, D_{t2}, \dots, D_{tn}, t_F, t_{FP}, C_{t1}, \dots, C_{tn}$ (in Tone mode)
 Dial out : $D_{p1}, D_{p2}, \dots, D_{pn}, t_F, t_{FP}, C_{p1}, \dots, C_{pn}$ (in Pulse mode)
 LNB : $C_1, C_2 \dots, C_n$

Handfree Function operation:

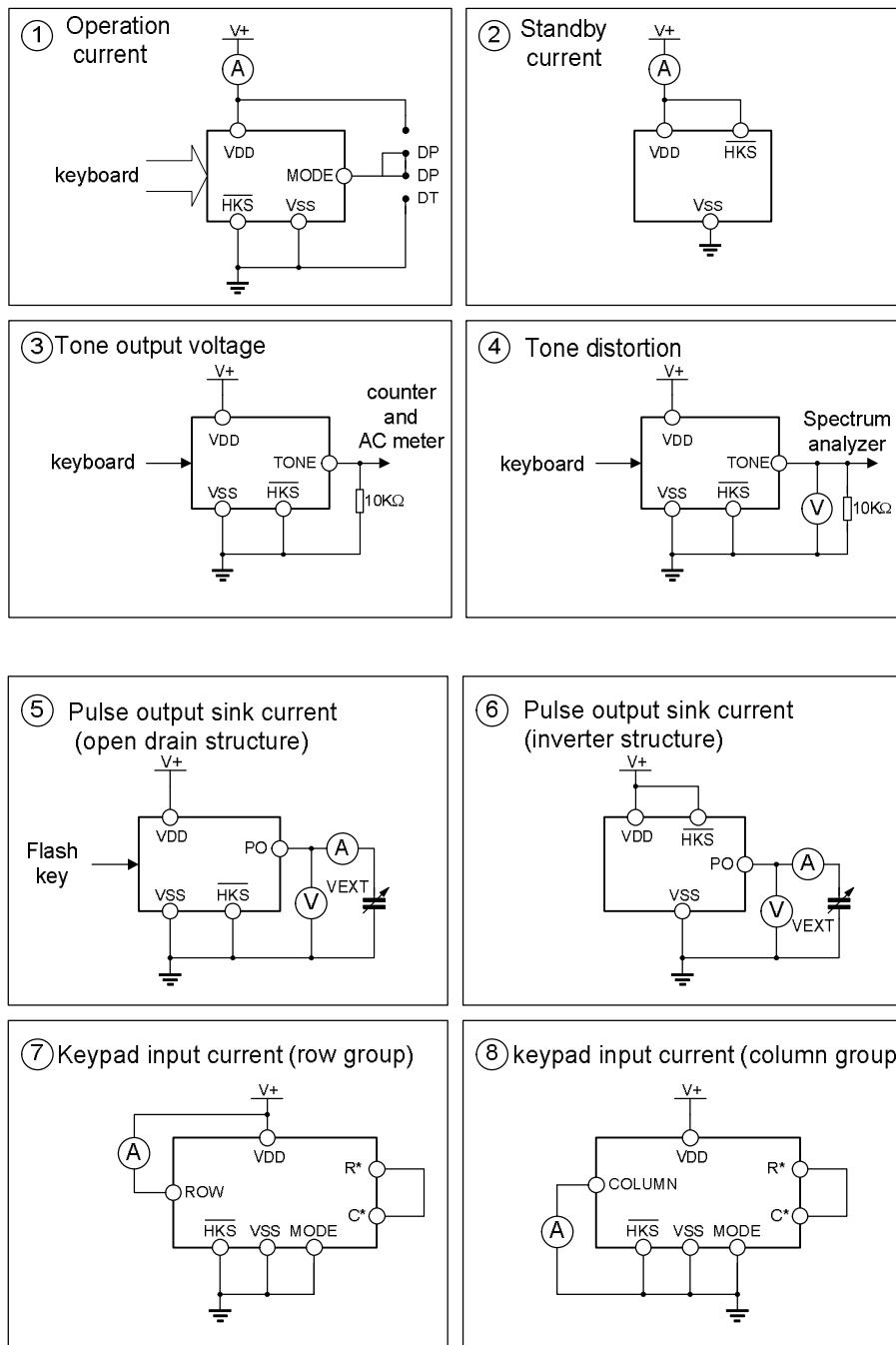
- A) To execute Handfree function: When HFO = 'low', HFI pin is active, the Handfree function will be enabled (HFO = 'high')
- B) Reset Handfree function:
- OFF-HOOK action.
 - When HFO = 'high', a HFI pin is active again, the Handfree function will be reset (HFO='low').

Operating flow chart of Handfree


Note: ON: ON HKS; OFF: OFF HKS; HF: Pressed HF key

STATE NO.	PO	XMUTE	HFO
(0) INITIAL STATE	F	F	0
(1) ON HKS HF LINE	F	F	1
(2) OFF HKS LINE	F	F	0
(3) OFF HKS HF LINE	F	F	1

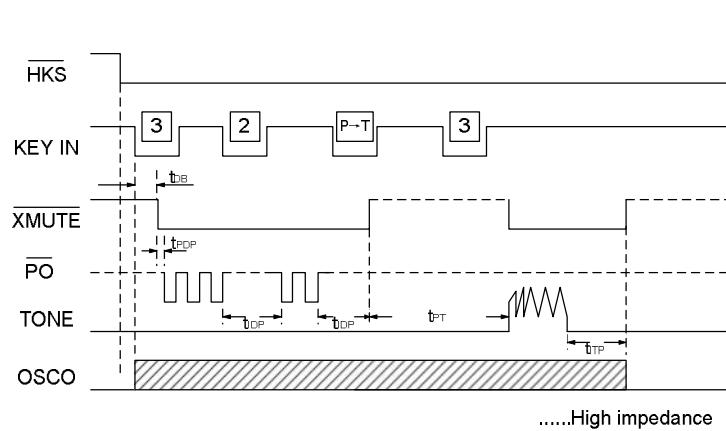
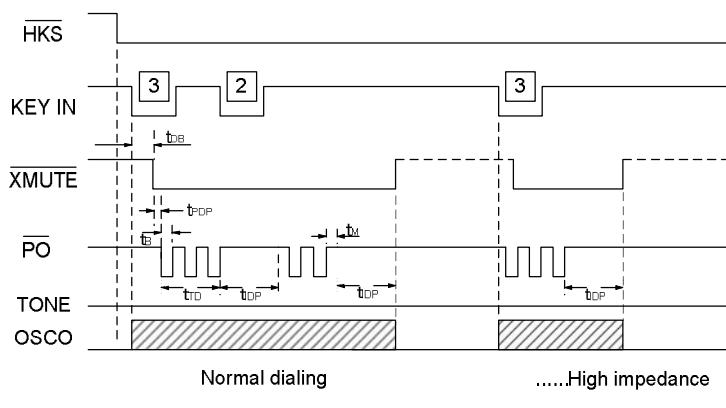
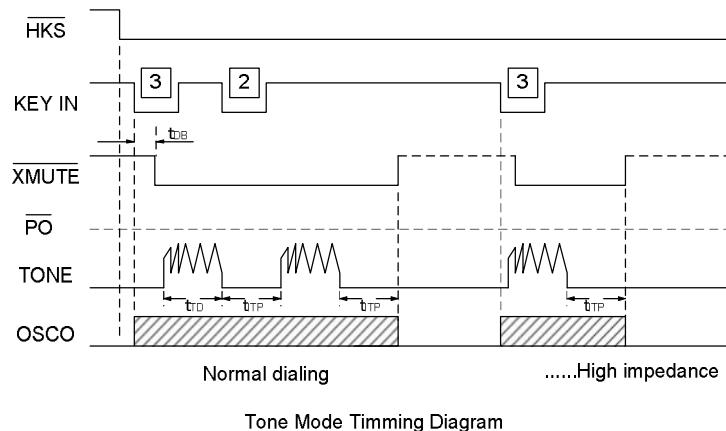
* F: Floating (Hi-impedance)

TEST CIRCUIT


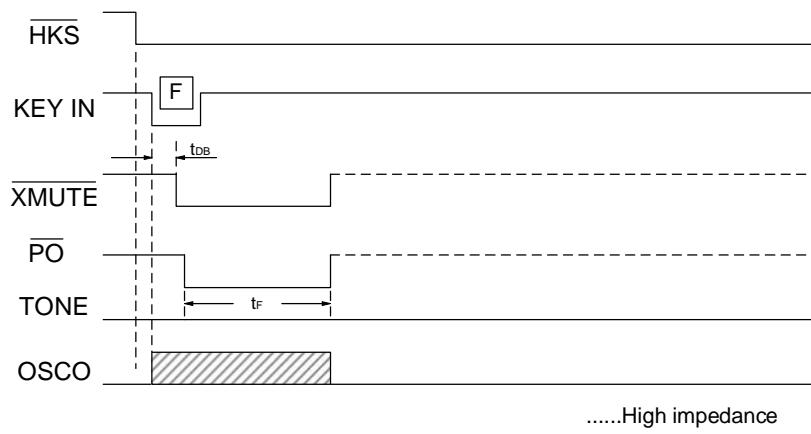
Note: 1. Dist. (dB)= $20\log\{[V_1^2+V_2^2+V_3^2+\dots V_n^2]^{1/2}\}/[(V_L^2+V_H^2)^{1/2}\}$

- a. V₁...V_n are extraneous frequencies (ie, inter modulation and harmonic), components in the 500Hz to 3400Hz band.
 - b. V_L, V_H are the individual frequency components of DTMF signal.
 - c. Whether keyboard is pushed refer to the TONE mode time diagram.
2. Sink current I_{link}=I/(1-Duty Cycle), I is the net DC current measured from ampere meter.
3. R*, C* mean other column and row.

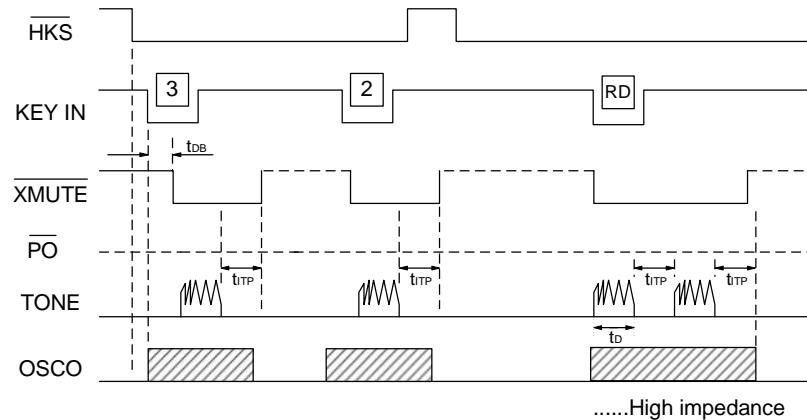
TIMING DIAGRAMS



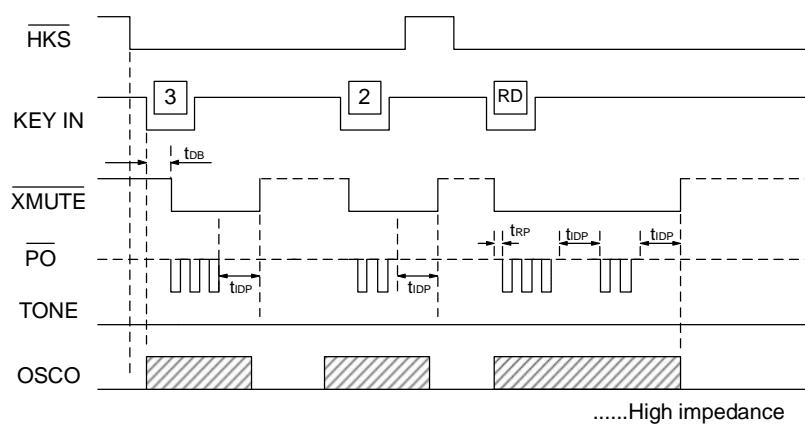
TIMING DIAGRAMS(continued)



Flash key operating timming

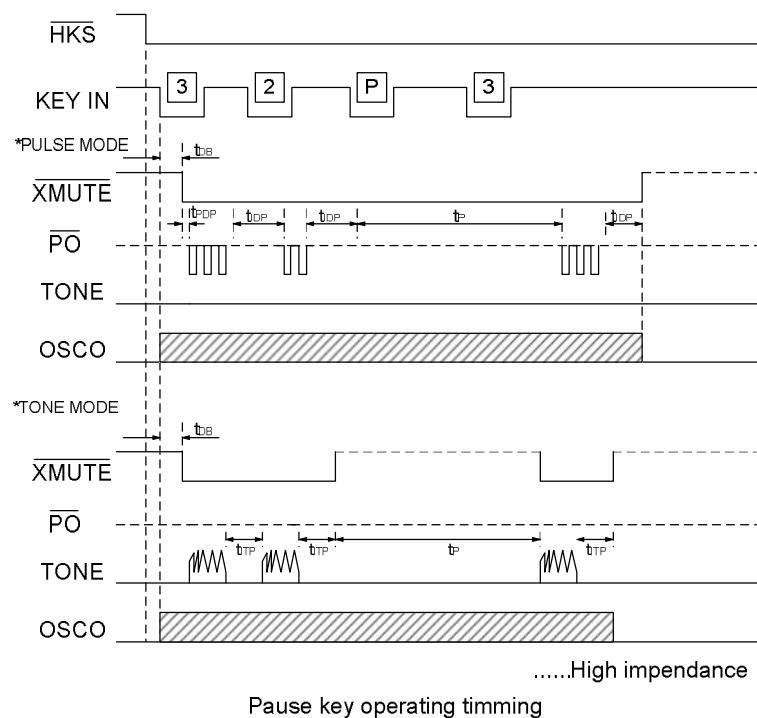


Tone Mode Redial Timming Diagram

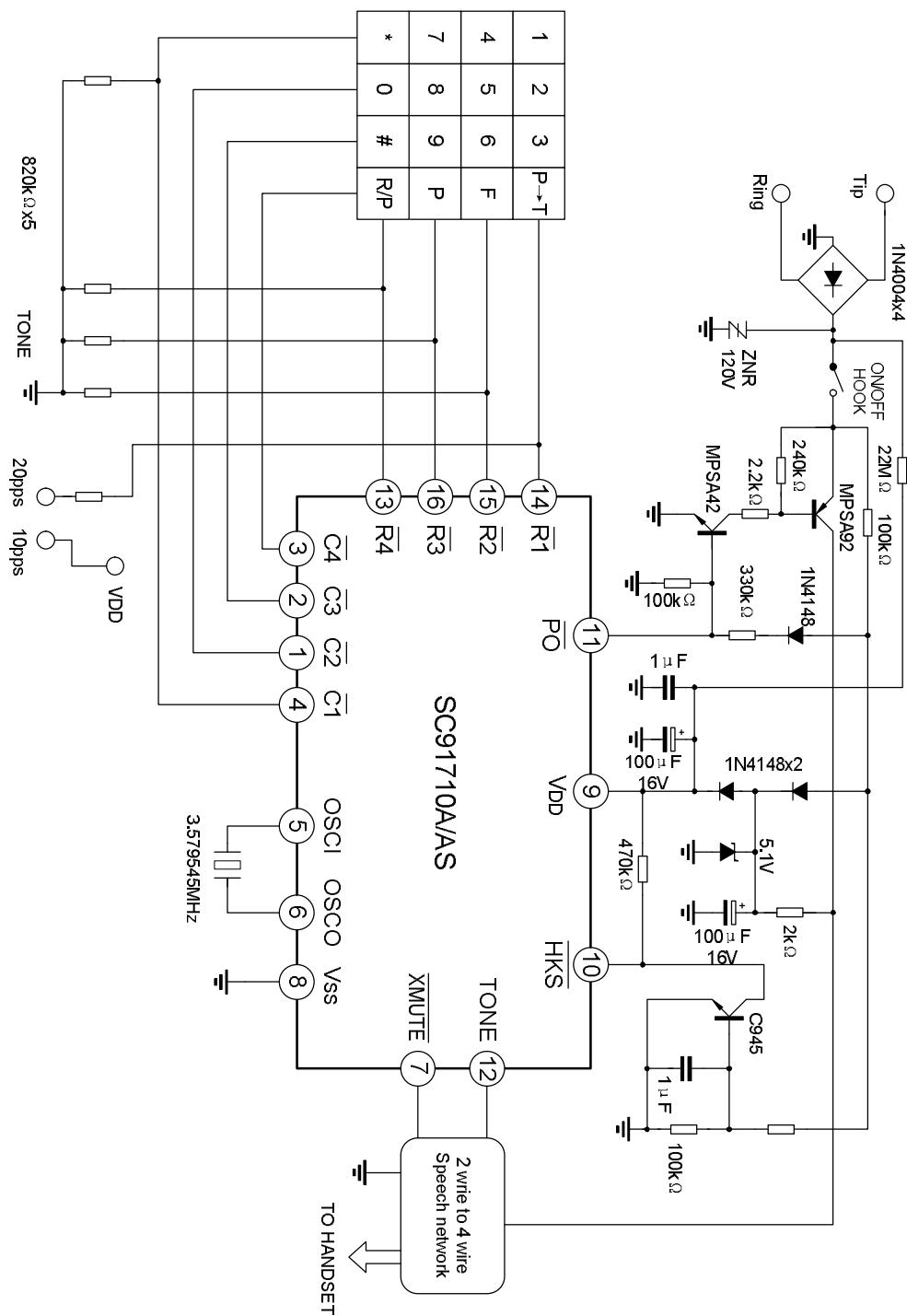


Pulse Mode Redial Timming Diagram

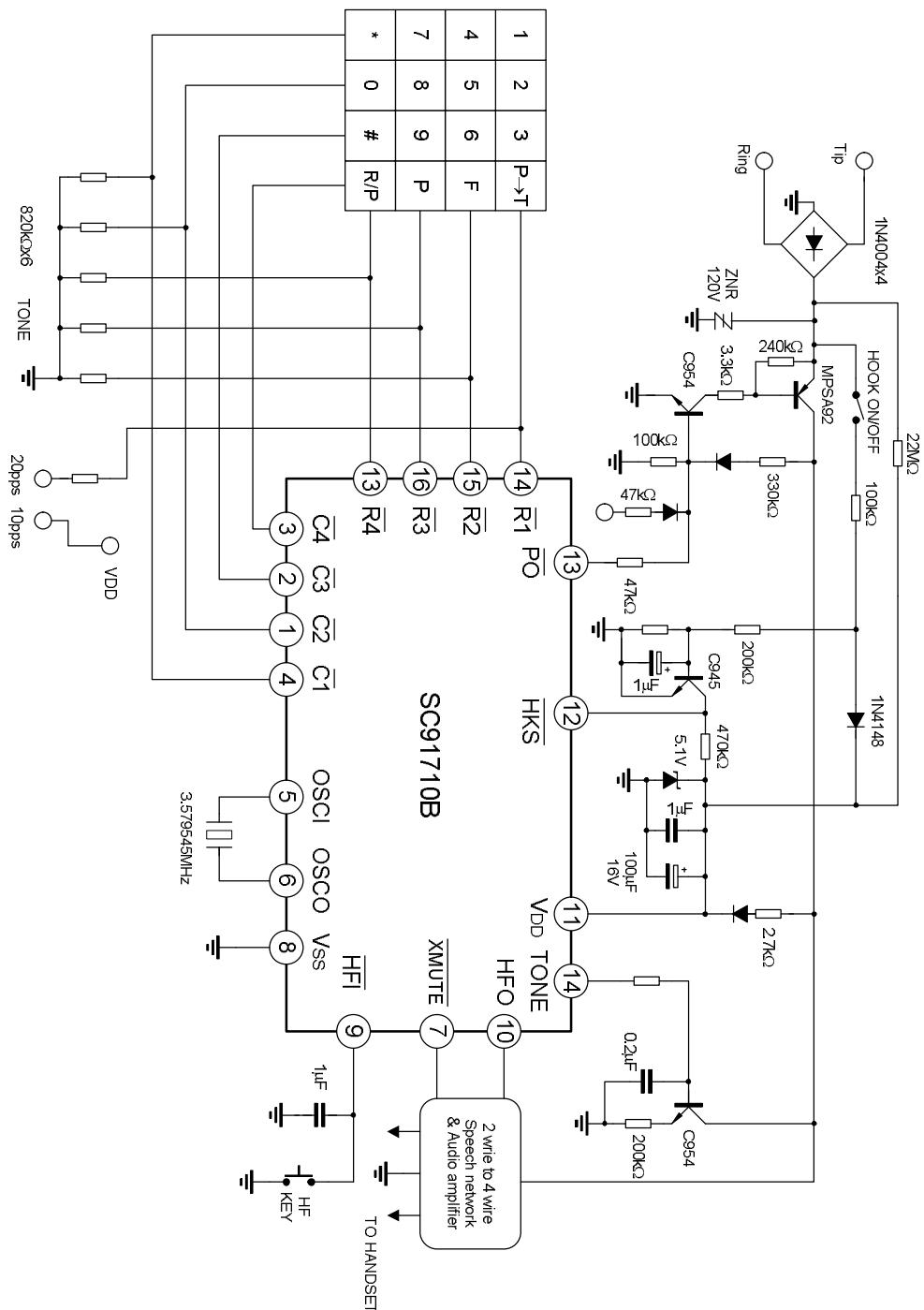
TIMING DIAGRAMS(continued)



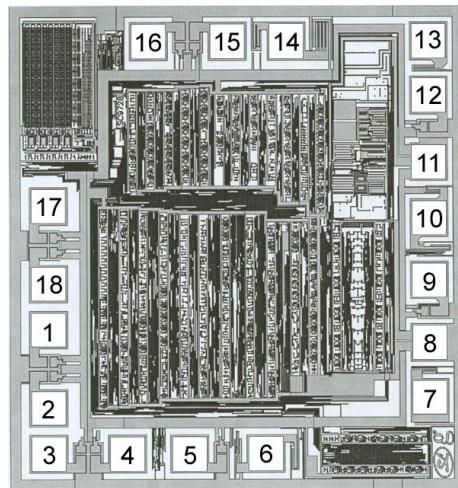
TYPICAL APPLICATION CIRCUIT



TYPICAL APPLICATION CIRCUIT



CHIP TOPOGRAPHY



Size: 1.45 x 1.54 mm²

PAD COORDINATES (Unit: μm)

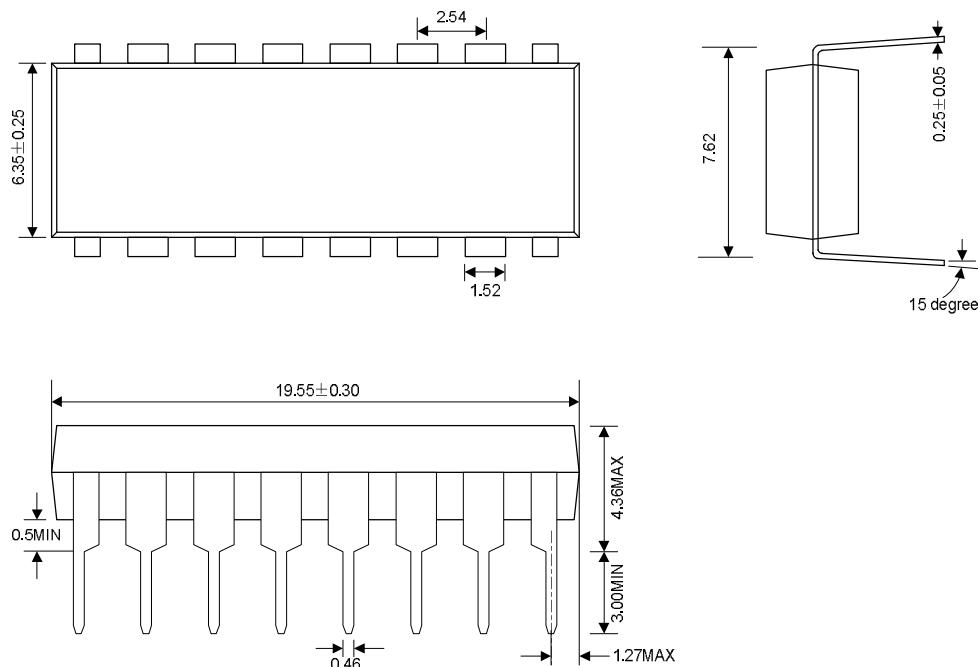
No.	Symbol	X	Y	No.	Symbol	X	Y
1	P1	-542.6	-238.0	10	P10	562.4	88.5
2	P2	-542.6	-468.1	11	P11	562.4	252.4
3	P3	-542.6	-602.5	12	P12	562.4	445.8
4	P4	-315.0	-602.5	13	P13	562.4	603.8
5	P5	-134.8	-602.5	14	P14	148.6	603.8
6	P6	85.5	-602.5	15	P15	-22.4	603.8
7	P7	562.4	-439.1	16	P16	-251.0	603.8
8	P8	562.4	-277.6	17	P17	-542.6	124.7
9	P9	562.4	-93.6	18	P18	-542.6	-102.9

Note: The original point of the coordinate is the die center.

PACKAGE OUTLINE

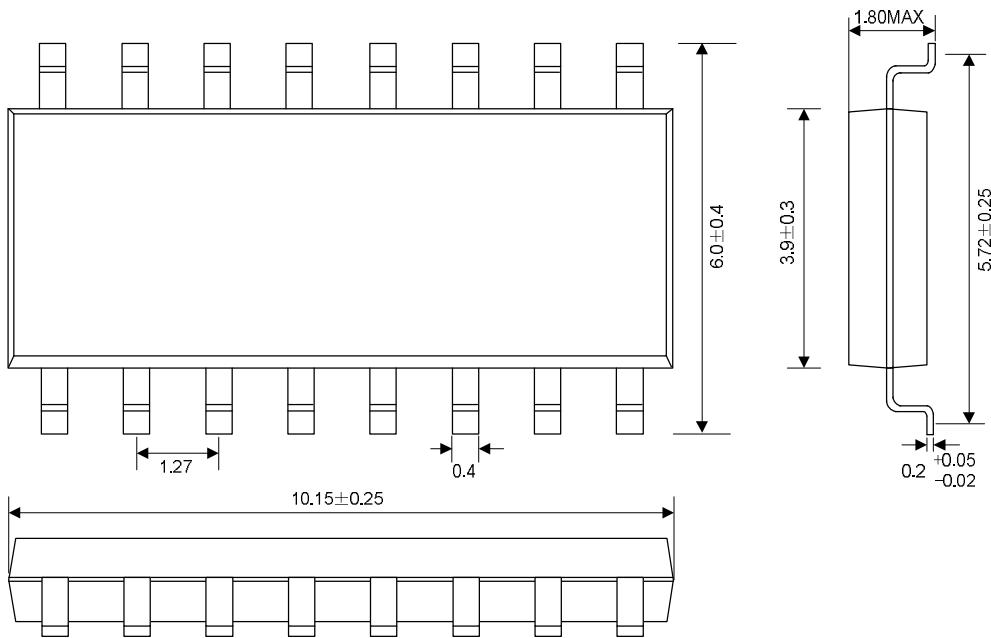
DIP-16-300-2.54

UNIT: mm

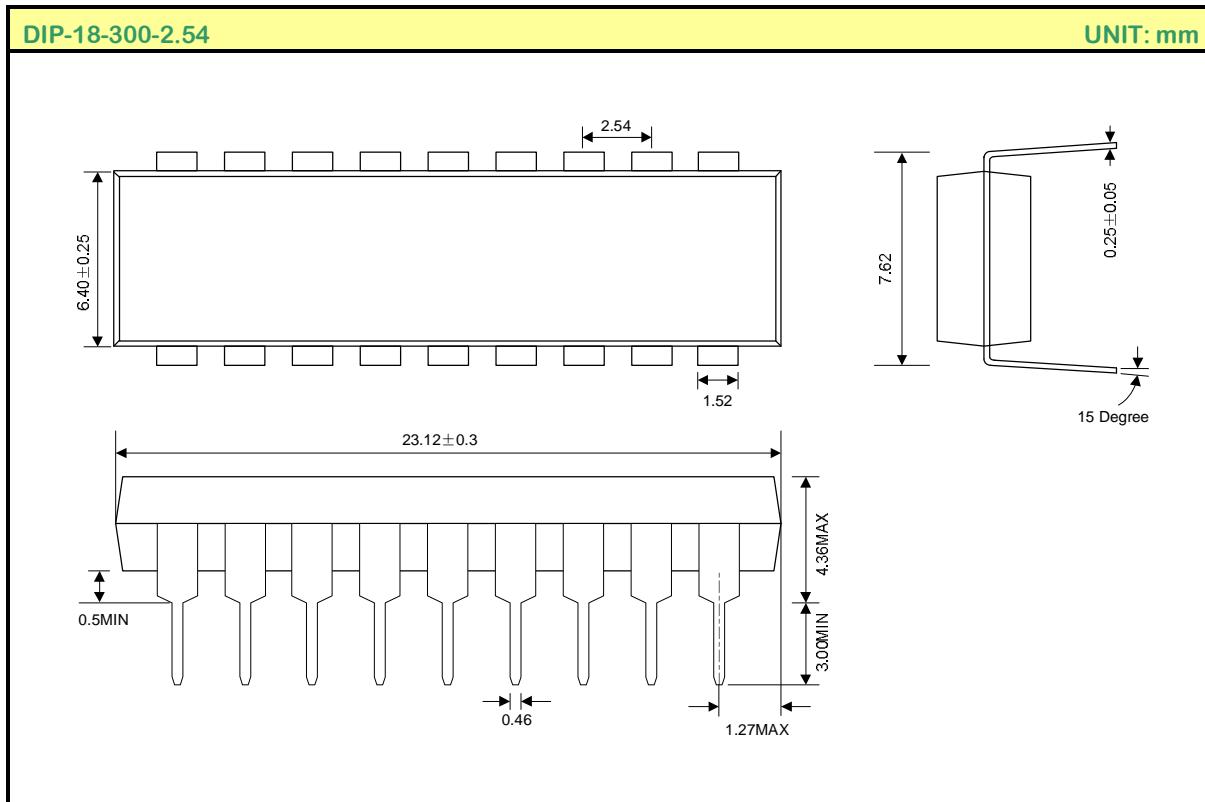


SOP-16-225-1.27

UNIT: mm



PACKAGE OUTLINE(Continued)



HANDLING MOS DEVICES:

Electrostatic charges can exist in many things. All of our MOS devices are internally protected against electrostatic discharge but they can be damaged if the following precautions are not taken:

- Persons at a work bench should be earthed via a wrist strap.
- Equipment cases should be earthed.
- All tools used during assembly, including soldering tools and solder baths, must be earthed.
- MOS devices should be packed for dispatch in antistatic/conductive containers.